



(12) **United States Patent**
Fay et al.

(10) **Patent No.:** **US 12,394,750 B2**
(45) **Date of Patent:** **Aug. 19, 2025**

(54) **SEMICONDUCTOR ASSEMBLIES WITH
REDISTRIBUTION STRUCTURES FOR DIE
STACK SIGNAL ROUTING**

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(*) Notice: Subject to any disclaimer, the term of this
patent is extended or adjusted under 35
U.S.C. 154(b) by 0 days.

(21) Appl. No.: **18/668,777**

(22) Filed: **May 20, 2024**

(65) **Prior Publication Data**
US 2024/0321822 A1 Sep. 26, 2024

Related U.S. Application Data
(63) Continuation of application No. 18/094,320, filed on
Jan. 6, 2023, now Pat. No. 11,990,446, which is a
(Continued)

(51) **Int. Cl.**
H01L 23/00 (2006.01)

(52) **U.S. Cl.**
CPC **H01L 24/82** (2013.01); **H01L 24/20**
(2013.01); **H01L 24/29** (2013.01); **H01L 24/45**
(2013.01);
(Continued)

(58) **Field of Classification Search**
CPC H01L 2924/1434; H01L 2924/1431; H01L
25/18; H01L 24/85; H01L 24/48;
(Continued)

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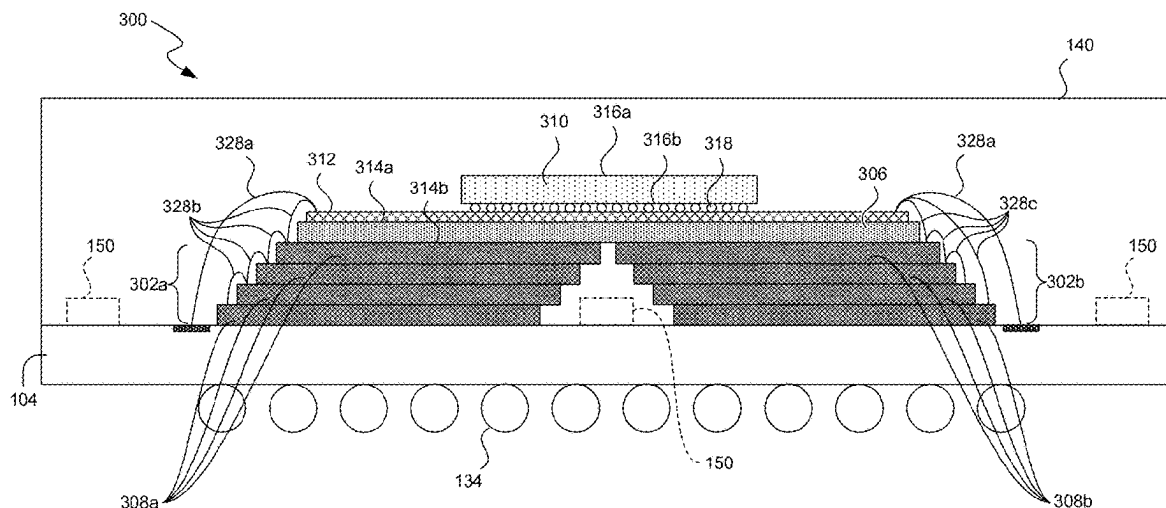
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(57) **ABSTRACT**

Semiconductor devices having redistribution structures, and associated systems and methods, are disclosed herein. In some embodiments, a semiconductor assembly comprises a die stack including a plurality of semiconductor dies, and a routing substrate mounted on the die stack. The routing substrate includes an upper surface having a redistribution structure. The semiconductor assembly also includes a plurality of electrical connectors coupling the redistribution structure to at least some of the semiconductor dies. The semiconductor assembly further includes a controller die mounted on the routing substrate. The controller die includes an active surface that faces the upper surface of the routing substrate and is electrically coupled to the redistribution structure, such that the routing substrate and the semiconductor dies are electrically coupled to the controller die via the redistribution structure.

20 Claims, 7 Drawing Sheets



Related U.S. Application Data

continuation of application No. 17/100,610, filed on
Nov. 20, 2020, now Pat. No. 11,552,045.

- (60) Provisional application No. 63/066,436, filed on Aug.
17, 2020.

(52) **U.S. Cl.**

CPC *H01L 24/83* (2013.01); *H01L 24/85*
(2013.01); *H01L 2224/82203* (2013.01); *H01L*
2924/1431 (2013.01); *H01L 2924/1434*
(2013.01)

(58) **Field of Classification Search**

CPC H01L 24/45; H01L 2225/0651; H01L
2225/06506; H01L 2224/48145
USPC 257/734
See application file for complete search history.

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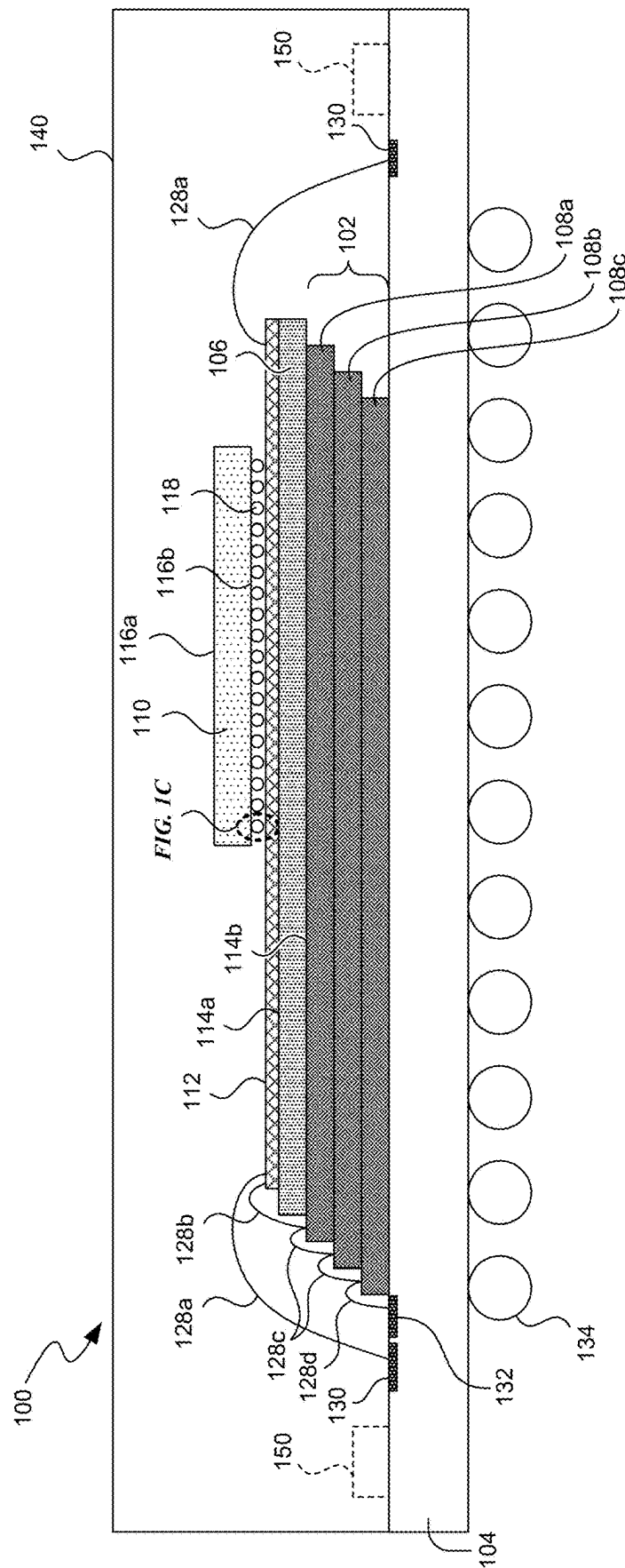
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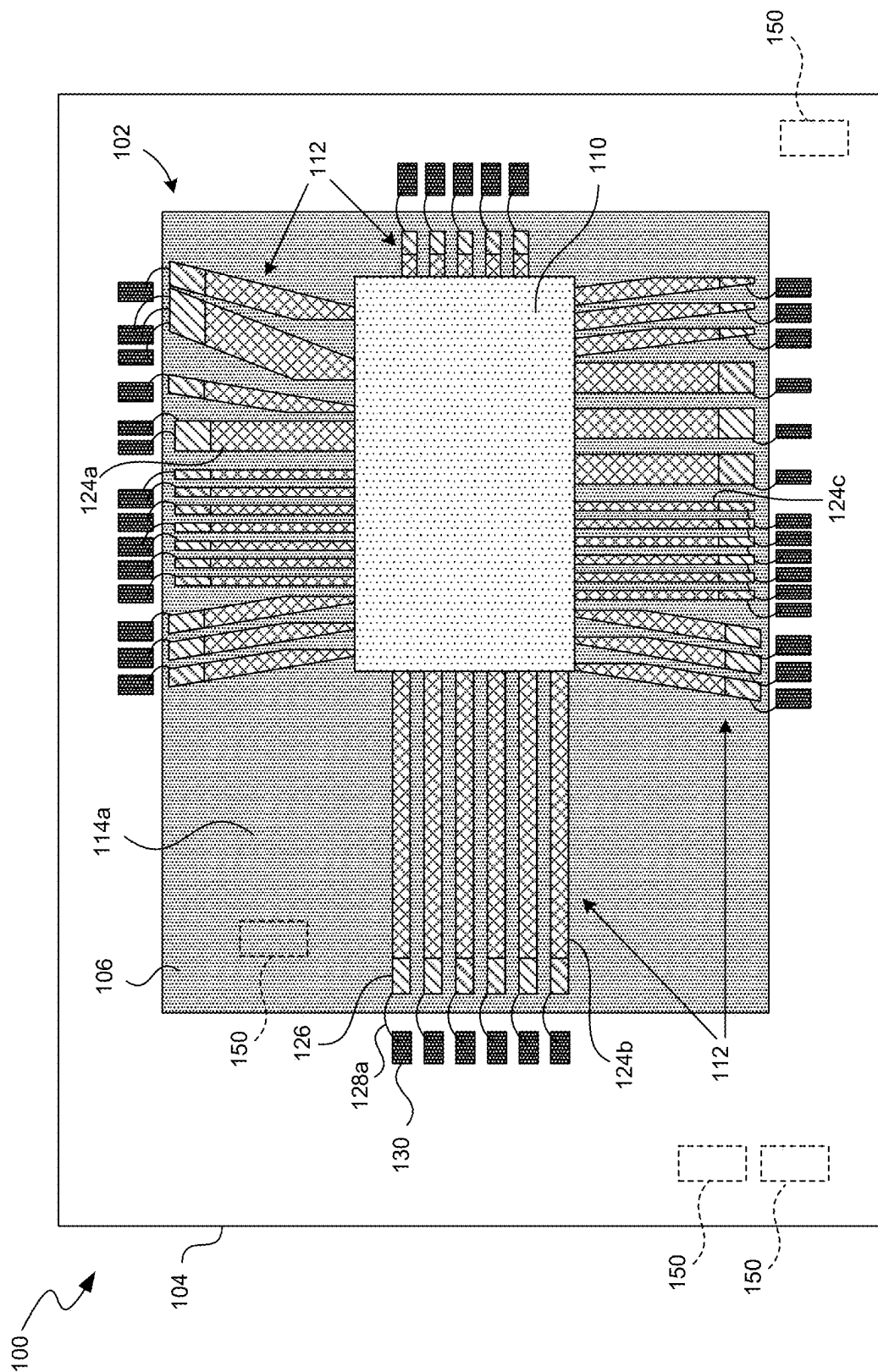


FIG. 1B

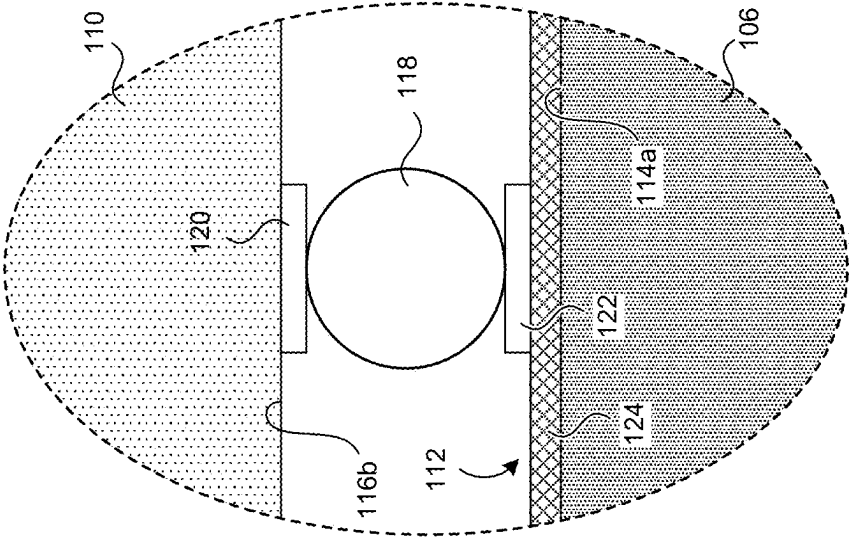


FIG. 1C

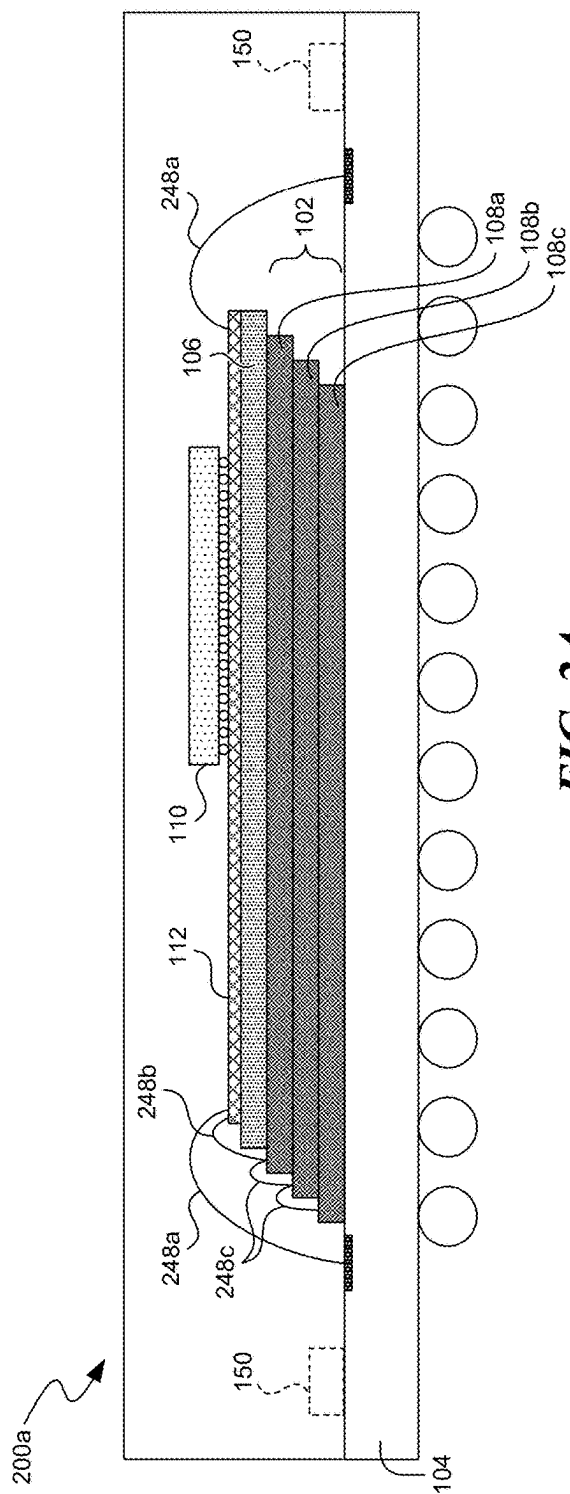


FIG. 2A

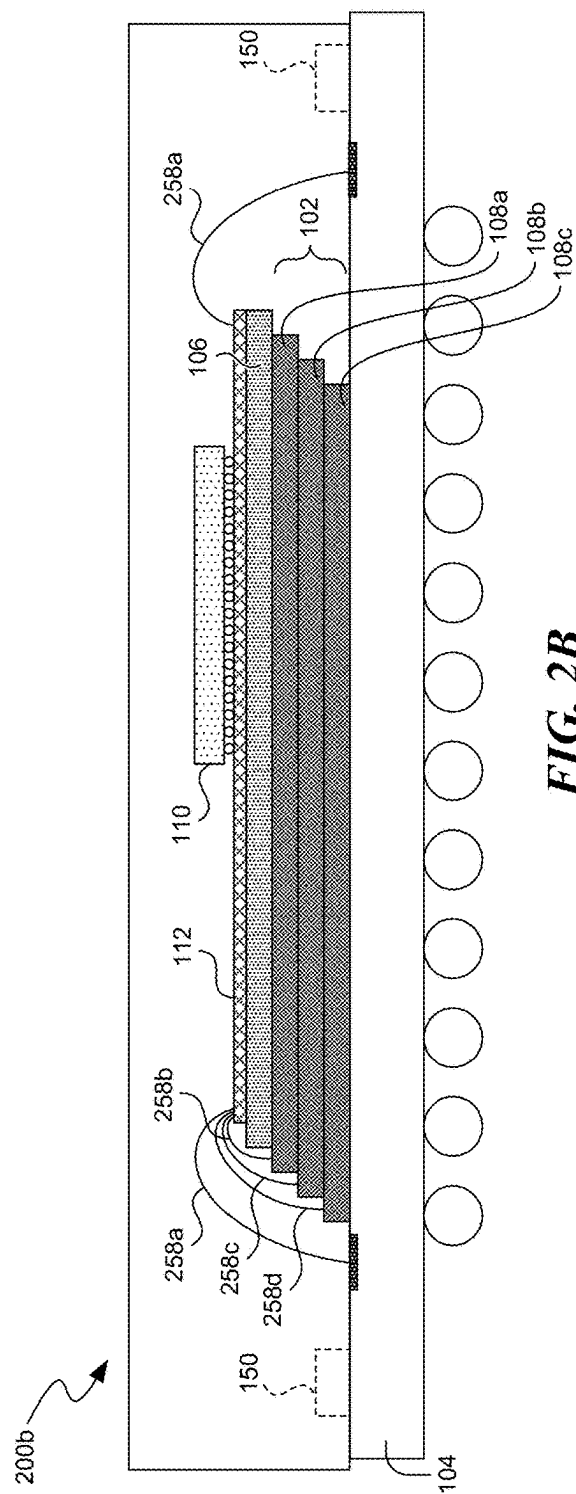


FIG. 2B

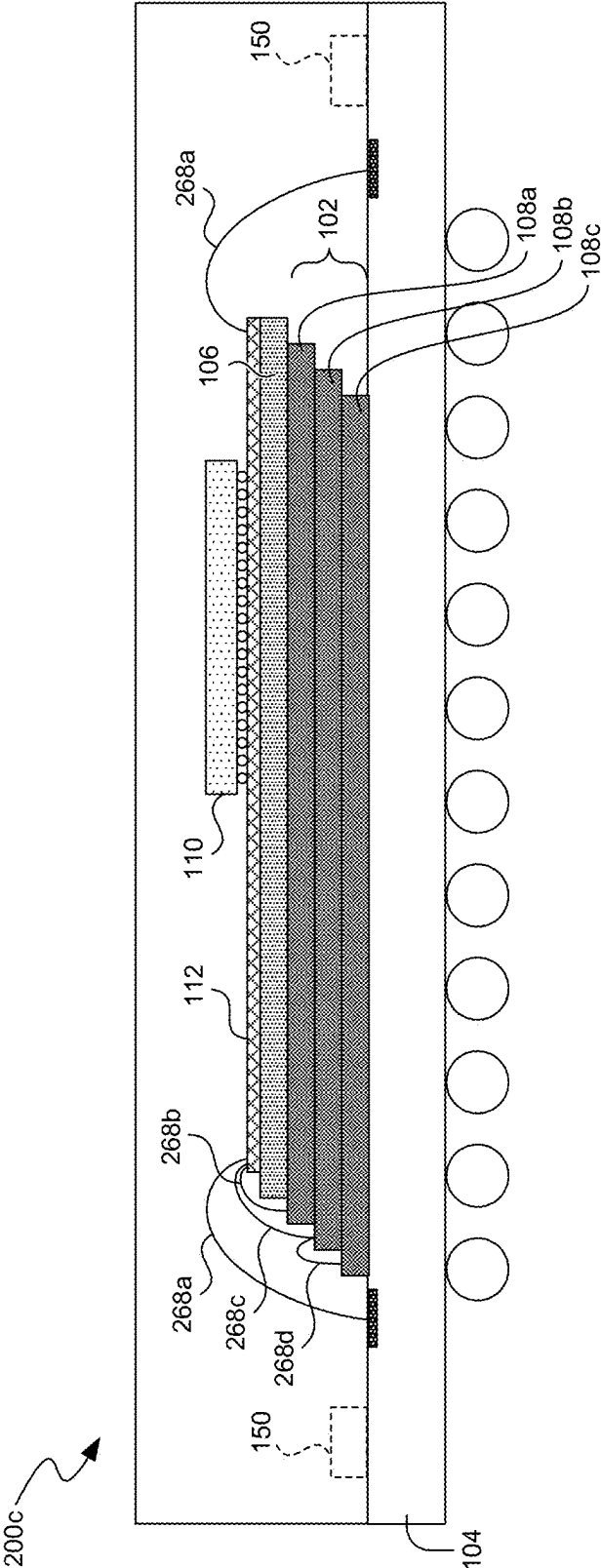
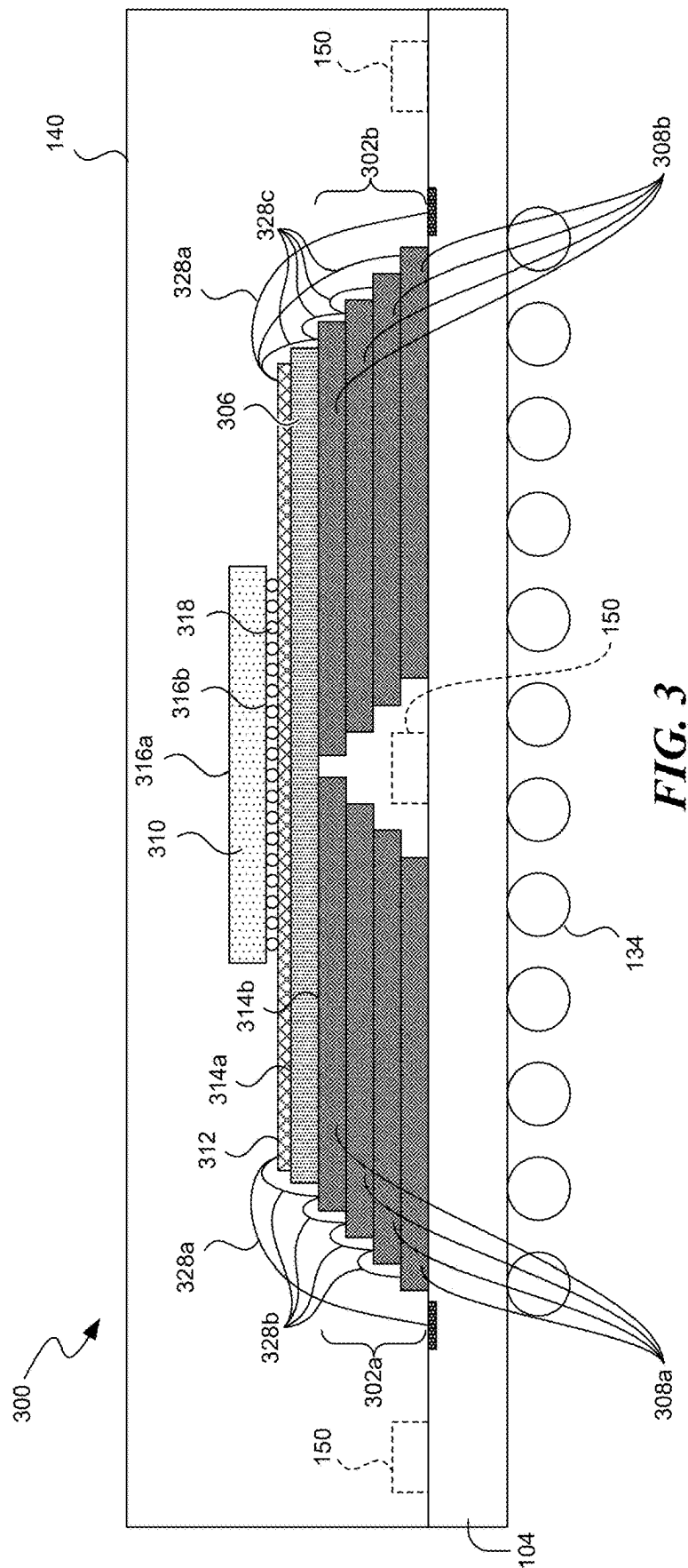
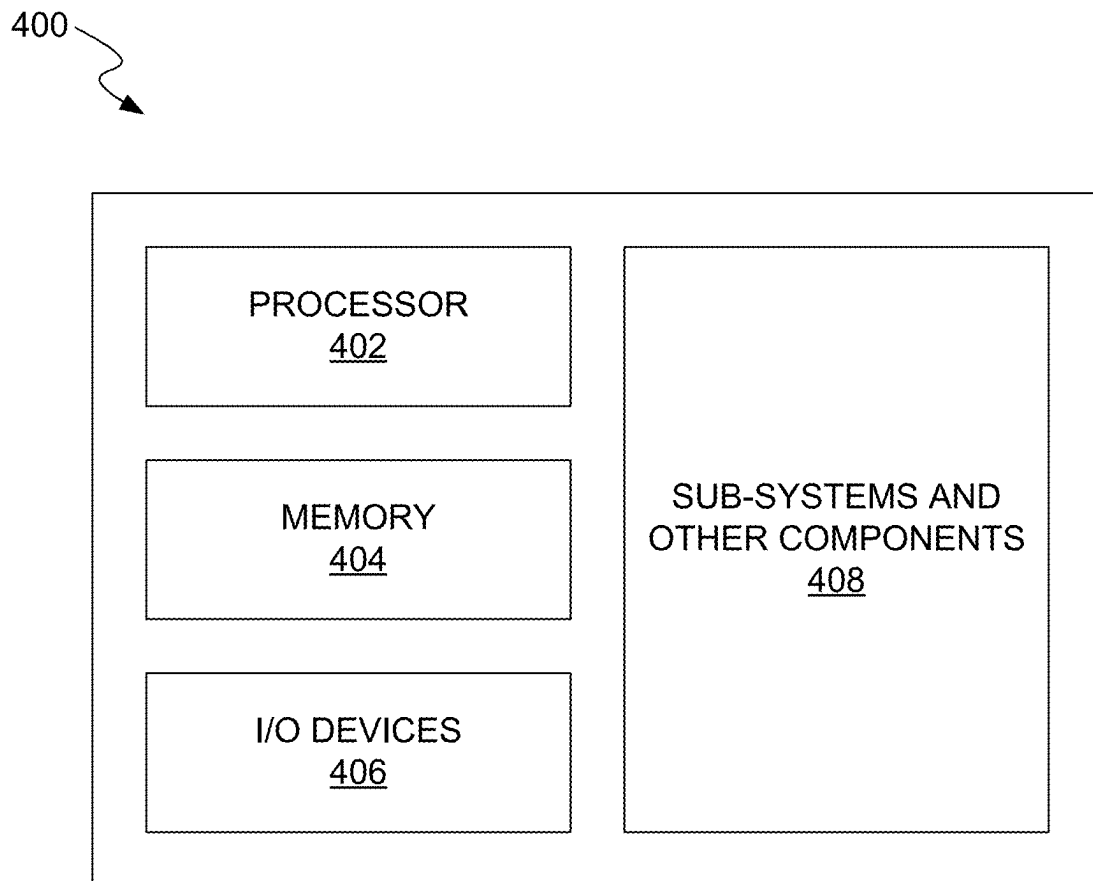


FIG. 2C



**FIG. 4**

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SEMICONDUCTOR ASSEMBLIES WITH REDISTRIBUTION STRUCTURES FOR DIE STACK SIGNAL ROUTING

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. patent application Ser. No. 18/094,320, filed Jan. 6, 2023; which is a continuation of U.S. patent application Ser. No. 17/100,610, filed Nov. 20, 2020, now U.S. Pat. No. 11,552,045; which claims the benefit of U.S. Provisional Application No. 63/066,436, filed Aug. 17, 2020; each of which is incorporated by reference herein in its entirety.

TECHNICAL FIELD

The present technology generally relates to semiconductor devices, and more particularly relates to semiconductor devices having redistribution structures configured to route signals between vertically stacked semiconductor dies.

BACKGROUND

Packaged semiconductor dies, including memory chips, microprocessor chips, and imager chips, typically include a semiconductor die mounted on a substrate and encased in a protective covering. The semiconductor die can include functional features, such as memory cells, processor circuits, and imager devices, as well as bond pads electrically connected to the functional features. The bond pads can be electrically connected to terminals outside the protective covering to allow the semiconductor die to be connected to higher level circuitry.

Market pressures continually drive semiconductor manufacturers to reduce the size of die packages to fit within the space constraints of electronic devices, while also driving them to increase the functional capacity of each package to meet operating parameters. One approach for increasing the processing power of a semiconductor package without substantially increasing the surface area covered by the package (the package's "footprint") is to vertically stack multiple semiconductor dies on top of one another in a single package. The dies in such vertically-stacked packages can be electrically coupled to each other and/or to a substrate via wires, interconnects, or other conductive structures. However, conventional techniques for routing signals to and from vertically-stacked semiconductor dies may rely on complicated multilayered routing structures within the package substrate, which may result in reduced signal integrity, larger package sizes, and increased manufacturing costs.

BRIEF DESCRIPTION OF THE DRAWINGS

Many aspects of the present technology can be better understood with reference to the following drawings. The components in the drawings are not necessarily to scale. Instead, emphasis is placed on illustrating clearly the principles of the present technology.

FIG. 1A is a side cross-sectional view of a semiconductor package configured in accordance with embodiments of the present technology.

FIG. 1B is a top view of the semiconductor package of FIG. 1A.

FIG. 1C is a closeup view of an interconnect structure of the semiconductor package of FIG. 1A.

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FIG. 2A is a side cross-sectional view of a semiconductor package including a plurality of electrical connectors configured in accordance with embodiments of the present technology.

FIG. 2B is a side cross-sectional view of another semiconductor package including a plurality of electrical connectors configured in accordance with embodiments of the present technology.

FIG. 2C is a side cross-sectional view of another semiconductor package including a plurality of electrical connectors configured in accordance with embodiments of the present technology.

FIG. 3 is a side cross-sectional view of a semiconductor package configured in accordance with embodiments of the present technology.

FIG. 4 is a schematic view of a system that includes a semiconductor device or package configured in accordance with embodiments of the present technology.

DETAILED DESCRIPTION

Specific details of several embodiments of semiconductor devices, and associated systems and methods, are described below. In some embodiments, for example, a semiconductor assembly includes one or more die stacks each having a plurality of semiconductor dies, and a routing substrate (e.g., another semiconductor die or an interposer) mounted on the die stack(s). The routing substrate includes an upper surface having a redistribution structure and a lower surface coupled to the uppermost semiconductor die(s) of the die stack(s). The redistribution structure can be coupled to some or all of the semiconductor dies via a plurality of electrical connectors (e.g., wirebonds). The semiconductor assembly can further include a controller die mounted on the routing substrate (e.g., via a flip chip process). The controller die can include an active surface that faces the upper surface of the routing substrate and is electrically coupled to the redistribution structure, such that the routing substrate and semiconductor dies are electrically coupled to the controller die via the redistribution structure. Accordingly, the redistribution structure and electrical connectors can route signals between the controller die and the die stack(s). In contrast to devices where the controller die is mounted on a package substrate and spaced apart from the die stack(s), the devices described herein can reduce and/or simplify the signal routing through the package substrate because the controller die can communicate with the die stack(s) via the redistribution structure and wirebonds (or other electrically connectors) instead of the package substrate. As a result, thinner and less complex package substrates can be used, which reduces package heights and manufacturing costs. The present technology can also improve signal integrity and impedance, such as reducing or eliminating crosstalk from overlapping signals that may arise with substrate routing, since the signals are routed through the redistribution structure. Additionally, the techniques described herein allow the controller die to be mounted directly onto the routing substrate via a flip chip process without any intervening spacers or supports, which may simplify the manufacturing process and further reduce the package size. Moreover, the routing substrate can be used to physically and electrically bridge multiple die stacks on a single package substrate, which can improve the mechanical strength of the overall package and mitigate warpage.

A person skilled in the relevant art will recognize that suitable stages of the methods described herein can be performed at the wafer level or at the die level. Therefore,

depending upon the context in which it is used, the term “substrate” can refer to a wafer-level substrate or to a singulated, die-level substrate. Furthermore, unless the context indicates otherwise, structures disclosed herein can be formed using conventional semiconductor manufacturing techniques. Materials can be deposited, for example, using chemical vapor deposition, physical vapor deposition, atomic layer deposition, plating, electroless plating, spin coating, and/or other suitable techniques. Similarly, materials can be removed, for example, using plasma etching, wet etching, chemical-mechanical planarization, or other suitable techniques.

Numerous specific details are disclosed herein to provide a thorough and enabling description of embodiments of the present technology. A person skilled in the art, however, will understand that the technology may have additional embodiments and that the technology may be practiced without several of the details of the embodiments described below with reference to FIGS. 1A-4. For example, some details of semiconductor devices and/or packages well known in the art have been omitted so as not to obscure the present technology. In general, it should be understood that various other devices and systems in addition to those specific embodiments disclosed herein may be within the scope of the present technology.

As used herein, the terms “vertical,” “lateral,” “upper,” “lower,” “above,” and “below” can refer to relative directions or positions of features in the semiconductor devices in view of the orientation shown in the Figures. For example, “upper” or “uppermost” can refer to a feature positioned closer to the top of a page than another feature. These terms, however, should be construed broadly to include semiconductor devices having other orientations, such as inverted or inclined orientations where top/bottom, over/under, above/below, up/down, and left/right can be interchanged depending on the orientation.

FIGS. 1A and 1B illustrate a semiconductor package 100 configured in accordance with embodiments of the present technology. More specifically, FIG. 1A is a side cross-sectional view of the package 100 and FIG. 1B is a top view of the package 100. The package 100 includes a die stack 102 mounted on a package substrate 104, and a routing substrate 106 (e.g., a semiconductor die or interposer) mounted on the die stack 102. The die stack 102 includes a plurality of vertically-stacked semiconductor dies 108a-c (collectively, “first dies 108”; the first dies 108 are omitted from FIG. 1B merely for purposes of clarity). The first dies 108 can be arranged in a shingled or stepped configuration in which each die is offset horizontally from the die below to allow for electrical interconnections, as discussed in greater detail below. Although FIG. 1A depicts the die stack 102 as including three first dies 108a-c, in other embodiments, the die stack 102 can include fewer or more first dies 108 (e.g., one, two, four, five, six, seven, eight, nine, ten, or more dies). The package 100 further includes a second semiconductor die 110 (“second die 110”) mounted on the routing substrate 106. The second die 110 can be a controller die (e.g., a microcontroller) that is configured to control the operations of the routing substrate 106 and/or first dies 108, as discussed in greater detail below.

The first and second dies 108, 110 can each include a semiconductor substrate (e.g., a silicon substrate, a gallium arsenide substrate, an organic laminate substrate, etc.). In some embodiments, the first and second dies 108, 110 each include a front and/or active surface having various types of semiconductor components. For example, the first dies 108 and/or the second die 110 can each have memory circuits

(e.g., dynamic random-access memory (DRAM), static random-access memory (SRAM), flash memory (e.g., NAND, NOR), or other type of memory circuits), controller circuits (e.g., DRAM controller circuits), logic circuits, processing circuits, circuit elements (e.g., wires, traces, interconnects, transistors, etc.), imaging components, and/or other semiconductor features. In some embodiments, the first dies 108 can each be arranged in a “face-up” configuration with their front surfaces oriented upward and away from the package substrate 104. In other embodiments, however, one or more of the first dies 108 can be in a “face-down” configuration with their front surfaces oriented downward and toward the package substrate 104. Optionally, one or more of the first dies 108 can be a “blank” substrate that does not include semiconductor components and that is formed from, for example, crystalline, semi-crystalline, and/or ceramic substrate materials, such as silicon, polysilicon, aluminum oxide (Al₂O₃), sapphire, and/or other suitable materials.

The routing substrate 106 includes a redistribution structure 112 configured to route signals (e.g., control signals, ONFI signals, power signals, test signals, etc.) between the second die 110 and the first dies 108 of the die stack 102. The redistribution structure 112 can also route signals between the second die 110 and the routing substrate 106, e.g., in embodiments where the routing substrate 106 is a semiconductor die or otherwise includes functional components. As best seen in FIG. 1A, the routing substrate 106 can include an upper (e.g., front) surface 114a and a lower (e.g., back) surface 114b, and the redistribution structure 112 can have pads or other terminals exposed at the upper surface 114a. In some embodiments, the redistribution structure 112 is or includes a redistribution layer (RDL) (e.g., formed after a wafer probe test) or an in-line redistribution layer (IRDL) (e.g., formed before a wafer probe test).

The redistribution structure 112 can include one or more electrically conductive components, such as contacts, traces, pads, pins, wiring, circuitry, and the like, and one or more dielectric materials. The electrically conductive components of the redistribution structure 112 can be made of any suitable conductive material, such as one or more metals (e.g., copper, gold, titanium, tungsten, cobalt, nickel, platinum, etc.), metal-containing compositions (e.g., metal silicide, metal nitride, metal carbide, etc.), and/or conductively-doped semiconductor materials (e.g., conductively-doped silicon, conductively-doped germanium, etc.). Although FIG. 1A illustrates the redistribution structure 112 as having a single routing or metallization layer, in other embodiments, the redistribution structure 112 can include multiple routing or metallization layers (e.g., two, three, four, five, or more layers).

The routing substrate 106 can be any component that is a suitable substrate for fabricating the redistribution structure 112. In some embodiments, the routing substrate 106 is a semiconductor die, e.g., a semiconductor die having features similar to the first and/or second dies 108, 110. For example, the routing substrate 106 can be a memory die (e.g., a NAND die, an SRAM die, etc.), and the first dies 108 can also be memory dies (e.g., NAND dies). Alternatively, the routing substrate 106 can be an interposer, such as an inorganic interposer (e.g., silicon, glass, ceramic, etc.) or an organic interposer (e.g., FR-4, polyimide, a coreless laminate, etc.). The redistribution structure 112 can be formed on the routing substrate 106 using any suitable techniques known to those of skill in the art, such as semiconductor fabrication processes (e.g., if the routing substrate 106 is a semiconductor die, inorganic interposer, or other inorganic

substrate) or circuit board manufacturing processes (e.g., if the routing substrate **106** is an organic interposer or other organic substrate).

Optionally, the routing substrate **106** can include other functional components in addition to the redistribution structure **112**. For example, the routing substrate **106** can include active circuit elements (e.g., transistors, memory circuits, controller circuits, logic circuits, or other semiconductor components) and the redistribution structure **112** is formed on or over the active circuit elements. In some embodiments, the routing substrate **106** is a memory die (e.g., a NAND die, SRAM die, etc.) and the redistribution structure **112** is formed on or over the memory circuits of the memory die. As another example, the routing substrate **106** can include passive circuit elements, such as capacitors, inductors, and/or resistors. The passive circuit elements can be formed in the routing substrate **106** using semiconductor fabrication techniques, or can be surface-mounted components attached to the routing substrate **106**, as discussed in greater detail below. In other embodiments, however, the routing substrate **106** can be used solely to route signals between the second die **110** and the first dies **108** of the die stack **102**, and may not include any additional active and/or passive circuit elements.

The second die **110** is electrically and mechanically coupled to the redistribution structure **112** on the routing substrate **106** by interconnect structures **118**. As best seen in FIG. 1A, the second die **110** can include an upper (e.g., back) surface **116a** and a lower (e.g., active and/or front) surface **116b**. The second die **110** can be mounted to the routing substrate **106** in a face-to-face (F2F) configuration in which the lower surface **116b** of the second die **110** faces the upper surface **114a** and redistribution structure **112** of the routing substrate **106**. In some embodiments, the second die **110** is connected directly to the routing substrate **106** without any intervening spacers, supports, other dies, etc., between the second die **110** and the routing substrate **106**.

Referring to FIGS. 1A and 1C together (FIG. 1C is a closeup view of an interconnect structure **118** of FIG. 1A), the interconnect structures **118** can be bumps, micro-bumps, pillars, columns, studs, etc., between the lower surface **116b** of the second die **110** and the redistribution structure **112**. As shown in FIG. 1C, each interconnect structure **118** can connect a pin or pad **120** on the second die **110** (e.g., a data pin, an address pin, a control pin, etc.) to a corresponding contact **122** of the redistribution structure **112**. Although FIG. 1C illustrates a single pin **120** and a single contact **122**, one skilled in the art will appreciate that the second die **110** can include a plurality of pins **120** and the redistribution structure **112** can include a corresponding plurality of contacts **122**. The interconnect structures **118** can include any suitably conductive material such as copper, nickel, gold, silicon, tungsten, solder (e.g., SnAg-based solder), conductive-epoxy, combinations thereof, etc., and can be formed by electroplating, electroless-plating, or another suitable process. In some embodiments, the interconnect structures **118** also include barrier materials (e.g., nickel, nickel-based intermetallic, and/or gold; not shown) formed over end portions of the interconnect structures **118**. The barrier materials can facilitate bonding and/or prevent or at least inhibit the electromigration of copper or other metals used to form the interconnect structures **118**. Optionally, the interconnect structures **118** can be surrounded by an underfill material (not shown) between the routing substrate **106** and second die **110**.

Referring to FIGS. 1B and 1C together, the redistribution structure **112** can include a plurality of traces **124** extending

over the upper surface **114a** of the routing substrate **106** to route signals from the second die **110** to the periphery of the routing substrate **106**. The second die **110** can be located at the interior portion of the routing substrate **106** (FIG. 1B), and the traces **124** can extend from the locations of the interconnect structures **118** and contacts **122** (FIG. 1C) underneath the second die **110** to a plurality of bond pads **126** at the peripheral portions of the routing substrate **106**. Each trace **124** can electrically connect a respective contact **122** (FIG. 1C) to a corresponding bond pad **126** (FIG. 1B) at the peripheral portion of the routing substrate **106**. The traces **124** can be separated from each other by an insulating material (e.g., a dielectric material; not shown) to reduce or eliminate interference and/or cross-talk between individual traces **124**.

The number, geometry, and arrangement of the traces **124** can be designed to provide different signal routing configurations and can be customized for the particular device or package. The traces **124** shown in FIG. 1B can extend to each of the four edges of the routing substrate **106**. In other embodiments, however, the traces **124** can extend to fewer edges of the routing substrate **106**, such as one edge, two edges, or three edges. Additionally, some or all of the traces **124** can have different geometries (e.g., different lengths, widths, shapes, etc.). For example, trace **124a** is wider than trace **124b**, which is wider than trace **124c**. In some embodiments, the different geometries are used to accommodate different types of signals, e.g., wider traces can be used for power delivery, while narrower traces can be used for high speed data signals.

Referring again to FIGS. 1A and 1B together, the package **100** further includes a plurality of electrical connectors **128a-d** (e.g., wirebonds) coupling the redistribution structure **112**, package substrate **104**, and first dies **108** to each other to route signals (e.g., control signals, ONFI signals, power signals, test signals, etc.) between these components. In some embodiments, the ends of each electrical connector are attached to respective bond pads on the corresponding package components (the bond pads on the redistribution structure **112** and first dies **108** are omitted in FIG. 1A merely for purposes of clarity). For example, the redistribution structure **112** can be electrically coupled to the package substrate **104** via one or more electrical connectors **128a** extending between bond pads **126** of the redistribution structure **112** (FIG. 1B) and corresponding bond pads **130** on the package substrate **104**. Accordingly, the redistribution structure **112** and electrical connectors **128a** can route signals directly between the second die **110** and the package substrate **104** (e.g., power signals, signals to and/or from a host device).

The redistribution structure **112** and electrical connectors **128b-c** can route signals between the second die **110** and each of the first dies **108** of the die stack **102**. In the illustrated embodiment, for example, the package **100** includes at least one electrical connector **128b** electrically coupling the redistribution structure **112** to the uppermost first die **108a** to route signals directly between the second die **110** and the uppermost first die **108a**. The package **100** can also include a cascading series of electrical connectors **128c** connecting the first dies **108a-c** to each other. For example, the uppermost first die **108a** is electrically coupled to the first die **108b** by one electrical connector **128c**, and the first die **108b** is electrically coupled to the lowermost first die **108c** by another electrical connector **128c**. Accordingly, the redistribution structure **112**, electrical connectors **128b-c**, and uppermost first die **108a** can collectively route signals between the second die **110** and the first die **108b**. Similarly,

the redistribution structure **112**, electrical connectors **128b-c**, and first dies **108a-b** can collectively route signals between the second die **110** and the lowermost first die **108c**. Optionally, the package **100** can include at least one electrical connector **128d** that electrically couples the lowermost first die **108c** directly to the package substrate **104**. The electrical connector **128d** can route signals (e.g., test signals) directly between the lowermost first die **108c** and the package substrate **104**.

Although in the configuration of FIGS. 1A and 1B the electrical connectors **128a-d** are depicted as wirebonds, the package **100** can include other types of electrical connectors for electrically coupling the redistribution structure **112**, package substrate **104**, routing substrate **106**, and/or first dies **108** to each other. In other embodiments, for example, any of the die-to-die connections (e.g., between the routing substrate **106** and the uppermost first die **108a** and/or between any of the first dies **108**) and/or die-to-substrate connections (e.g., between the lowermost first die **108c** and the package substrate **104**) shown in FIGS. 1A and 1B can instead be implemented using through-silicon vias (TSVs), interconnect structures (e.g., bumps, micro-bumps, pillars, columns, studs, etc.), and/or any other interconnection techniques known to those of skill in the art. Moreover, in other embodiments, one or more of the electrical connectors **128a-d** can be omitted. Additional examples of configurations for the electrical connectors **128a-d** are discussed further below with respect to FIGS. 2A-2C.

The package substrate **104** can be or include an interposer, a printed circuit board, a dielectric spacer, another semiconductor die (e.g., a logic die), or another suitable substrate. In some embodiments, the package substrate **104** includes additional semiconductor components (e.g., doped silicon wafers or gallium arsenide wafers), nonconductive components (e.g., various ceramic substrates, such as aluminum oxide (Al₂O₃), etc.), aluminum nitride, and/or conductive portions (e.g., interconnecting circuitry, TSVs, etc.). The package substrate **104** can further include electrical connectors **134** (e.g., solder balls, conductive bumps, conductive pillars, conductive epoxies, and/or other suitable electrically conductive elements) electrically coupled to the package substrate **104** and configured to electrically couple the package **100** to an external device (not shown), such as a host device as discussed further below. Optionally, the package substrate **104** can include one or more signal routing structures or layers (not shown) including electrically conductive components such as traces, vias, etc., that transmit signals between the electrical connectors **134** and the second die **110** and/or die stack **102**. As previously discussed, the configuration of the die stack **102**, second die **110**, and redistribution structure **112** described herein can reduce routing signals via the package substrate **104**, such that the package substrate **104** can be thinner and/or less complex compared to conventional systems that route the controller signals through the package substrate. For example, the package substrate **104** can include no more than one, two, three, or four signal routing layers. The package substrate **104** can have a thickness less than or equal to 250 μm , 200 μm , 150 μm , 125 μm , 100 μm , or 75 μm .

The package **100** can further include a mold material or encapsulant **140** formed over at least a portion of the package substrate **104** and/or at least partially around the routing substrate **106** and the first and second dies **108**, **110** (the mold material **140** is omitted from FIG. 1B merely for purposes of clarity). The mold material **140** can be a resin, epoxy resin, silicone-based material, polyimide, or any other material suitable for encapsulating the routing substrate **106**,

the first and second dies **108**, **110**, and/or at least a portion of the package substrate **104** to protect these components from contaminants and/or physical damage.

Optionally, the package **100** can include surface-mounted components **150** (best seen in FIGS. 1A and 1B), such as capacitors, resistors, inductors, and/or other circuit elements. The surface-mounted components can be on the package substrate **104** (e.g., at peripheral portions away from the die stack **102** and bond pads **130**), on the routing substrate **106** (e.g., at locations away from the traces **124** and the second die **110**—FIG. 1B), and/or any other suitable location. In some embodiments, the semiconductor package **100** includes other components such as external heatsinks, a casing (e.g., thermally conductive casing), electromagnetic interference (EMI) shielding components, etc.

In some embodiments, the package **100** is operably connected to a host device (not shown) via the electrical connectors **134**. The host device can be a computing device such as a desktop or portable computer, a server, a hand-held device (e.g., a mobile phone, a tablet, a digital reader, a digital media player), or some component thereof (e.g., a central processing unit, a co-processor, a dedicated memory controller, etc.). The host device can be a networking device (e.g., a switch, a router, etc.), a recorder of digital images, audio and/or video, a vehicle, an appliance, a toy, or any one of a number of other products. In some embodiments, the host device is connected directly to the package **100**, while in other embodiments, the host device can be indirectly connected to the package **100** (e.g., over a networked connection or through intermediary devices).

For example, in some embodiments, the package **100** is a memory device and is configured to connect to a host device that utilizes memory for the temporary or persistent storage of information, or a component thereof. In such embodiments, the first dies **108** can be memory dies (e.g., NAND memory dies), and the second die **110** can be a memory controller. The routing substrate **106** can also be a memory die (e.g., a NAND memory die, an SRAM memory die). For example, the routing substrate **106** can be an SRAM memory die or other memory die that provides data storage for the operations of the memory controller. Alternatively, the routing substrate **106** may not include any memory circuits and may function solely to route signals between the memory controller and the individual memory dies. The memory device can include a plurality of external terminals that include command and address terminals coupled to a command bus and an address bus to receive command signals CMD and address signals ADDR, respectively. The memory device can further include a chip select terminal to receive a chip select signal CS, clock terminals to receive clock signals CK and CKF, data clock terminals to receive data clock signals WCK and WCKF, data terminals DQ, RDQS, DBI, and DMI to receive data signals, and/or power supply terminals VDD, VSS, and VDDQ.

The package **100** can be manufactured using any suitable process known to those of skill in the art. In some embodiments, for example, a manufacturing process for the package **100** includes forming the redistribution structure **112** on the routing substrate **106** using wafer-level or chip-level processes. Subsequently, the routing substrate **106** is mounted on the die stack **102** (e.g., via die attach film or other suitable techniques). The die stack **102** can be mounted on the package substrate **104** before, during, or after the routing substrate **106** is mounted on the die stack **102**. The second die **110** can be mounted on the routing substrate **106** before, during, or after the routing substrate **106** is mounted on the die stack **102**. In some embodiments, the second die **110** is

mechanically and electrically coupled to the routing substrate **106** via the interconnect structures **118** using a thermocompression bonding (TCB) operation. The electrical connectors **128a-d** can then be formed and attached to the routing substrate **106**, the first and second dies **108**, **110**, and the package substrate **104** to electrically couple these components to each other, as discussed above.

FIGS. 2A-2C illustrate semiconductor packages with various arrangements of electrical connectors configured in accordance with embodiments of the present technology. The packages shown in FIGS. 2A-2C can be generally similar to the package **100** described with respect to FIGS. 1A-1C. Accordingly, like numbers are used to identify similar or identical components, and the description of the packages shown in FIGS. 2A-2C will be limited to those features that differ from the package **100** of FIGS. 1A-1C.

FIG. 2A illustrates a semiconductor package **200a** including a plurality of electrical connectors **248a-c** (e.g., wirebonds) for interconnecting the die stack **102**, the package substrate **104**, the routing substrate **106**, and the second die **110**. The electrical connectors **248a** couple the redistribution structure **112** directly to the package substrate **104**; the electrical connectors **248b** couple the redistribution structure **112** directly to the uppermost first die **108a**; and the cascading electrical connectors **248c** couple the first dies **108a-c** to each other in series. Unlike the package **100** of FIGS. 1A-1C, the package **200a** does not include any electrical connectors that couple the lowermost first die **108c** directly to the package substrate **104**. Instead, the electrical connectors **248a-c**, the redistribution structure **112**, and the first dies **108a-b** collectively route signals between the lowermost first die **108c** and the package substrate **104**.

FIG. 2B illustrates a semiconductor package **200b** including a plurality of electrical connectors **258a-d** (e.g., wirebonds) for interconnecting the die stack **102**, the package substrate **104**, the routing substrate **106**, and the second die **110**. The electrical connectors **258a** couple the redistribution structure **112** directly to the package substrate **104**. In the illustrated embodiment, each first die **108** is electrically coupled directly to the redistribution structure **112** via a respective set of electrical connectors. For example, the electrical connectors **258b** couple the uppermost first die **108a** directly to the redistribution structure **112**; the electrical connectors **258c** couple the first die **108b** directly to the redistribution structure **112**; and the electrical connectors **258d** couple the lowermost first die **108c** directly to the redistribution structure **112**. Accordingly, the redistribution structure **112** and the electrical connectors **258b-d** can transmit signals directly between the respective first die **108** and the second die **110**.

FIG. 2C illustrates a semiconductor package **200c** including a plurality of electrical connectors **268a-d** (e.g., wirebonds) for interconnecting the die stack **102**, the package substrate **104**, the routing substrate **106**, and the second die **110**. The electrical connectors **268a** couple the redistribution structure **112** directly to the package substrate **104**. In the illustrated embodiment, some of the first dies **108** are electrically coupled directly to the redistribution structure **112**, while some of first dies **108** are coupled indirectly via other first dies **108**. For example, the electrical connectors **268b-c** couple the first dies **108a-b**, respectively, directly to the redistribution structure **112**, to provide direct signal transmission between the second die **110** and each of the first dies **108a-b**. However, the lowermost first die **108c** is not coupled directly to the redistribution structure **112**. Instead, the electrical connector **268d** couples the lowermost first die **108c** to the first die **108b**, and the first die **108b** routes

signals between the lowermost first die **108c** and second die **110**. In other embodiments, however, the package **200c** can include different routing configurations between the second die **110** and the first dies **108**.

FIG. 3 is a schematic cross-sectional view of a semiconductor package **300** configured in accordance with embodiments of the present technology. The package **300** can be generally similar to the packages described with respect to FIGS. 1A-2C, except that the package **300** includes multiple die stacks (e.g., first die stack **302a** and second die stack **302b**) rather than a single die stack. Accordingly, like numbers are used to identify similar or identical components (e.g., routing substrate **306** versus routing substrate **106**), and the description of the package **300** will be limited to those features that differ from the packages of FIGS. 1A-2C.

The first and second die stacks **302a-b** are mounted on a package substrate **104**. The first and second die stacks **302a-b** can each be identical or generally similar to the die stack **102** of FIGS. 1A-1C. For example, the first die stack **302a** includes a first set of first semiconductor dies **308a** (e.g., a first set of memory dies) and the second die stack **302b** includes a second set of first semiconductor dies **308b** (e.g., a second set of memory dies). In the illustrated embodiment, the first and second die stacks **302a-b** are both arranged in a shingled configuration and are angled towards each other. In other embodiments, the first and second die stacks **302a-b** can be angled away from each other, angled in parallel directions, or any other suitable configuration. Additionally, although the first and second die stacks **302a-b** are depicted as each including four dies, in other embodiments, the first and/or second die stacks **302a-b** can include fewer or more dies (e.g., one, two, three, five, or more dies). The first and second die stacks **302a-b** can include the same number of dies and/or otherwise have the same or substantially similar heights.

The package **300** further includes a routing substrate **306** (e.g., another semiconductor die or an interposer) with a redistribution structure **312** formed on its upper surface **314a**. The routing substrate **306** can be the same or generally similar to the routing substrate **106** of FIGS. 1A-2C, except that the routing substrate **306** is mounted on multiple die stacks (e.g., the first and second die stacks **302a-b**). As shown in FIG. 3, the lower surface **314b** of the routing substrate **306** is coupled to the uppermost dies in each of the first and second die stacks **302a-b**. By bridging the first and second die stacks **302a-b**, the routing substrate **306** can increase the mechanical strength of the package **300** (e.g., improved three-point bending performance) and reduce warpage (e.g., due to heating during manufacturing and/or operation).

The redistribution structure **312** (e.g., an iRDL or RDL structure) is configured to route signals between the first and second die stacks **302a-b** and a second die **310** (e.g., a controller die) mounted on the routing substrate **306**. The redistribution structure **312** can be the same or generally similar to the redistribution structure **112** of FIGS. 1A-2C, except that the redistribution structure **312** routes signals to multiple die stacks (e.g., the first and second die stacks **302a-b**). Similarly, the second die **310** can be the same or generally similar to the second die **110** of FIGS. 1A-2C, except that the second die **310** communicates with multiple die stacks (e.g., the first and second die stacks **302a-b**). The second die **310** can include an upper (e.g., back) surface **316a** facing away from the routing substrate **306**, and a lower (e.g., active and/or front) surface **316b** facing toward the upper surface **314a** and redistribution structure **312** of the routing substrate **306**. The second die **310** can be

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electrically and mechanically coupled to the redistribution structure **312** via interconnect structures **318**.

In some embodiments, the redistribution structure **312** is electrically coupled to the package substrate **104**, the first die stack **302a**, and/or the second die stack **302b** via a plurality of electrical connectors **328a-c** (e.g., wirebonds). For example, the package **300** can include a set of electrical connectors **328a** connecting the redistribution structure **312** to the package substrate **104**, a set of electrical connectors **328b** connecting the redistribution structure **312** to the first set of first dies **308a** of the first die stack **302a**, and/or a set of electrical connectors **328c** connecting the redistribution structure **312** to the second set of first dies **308b** of the second die stack **302b**. Accordingly, the electrical connectors **328a-c** and redistribution structure **312** can route signals (e.g., control signals, ONFI signals, power signals, test signals, etc.) between the second die **310**, first die stack **302a**, second die stack **302b**, package substrate **104**, and/or routing substrate **306**. In the illustrated embodiment, the electrical connectors **328b** are arranged as a cascading series, while the electrical connectors **328c** include both cascading connectors and connectors that connect directly to individual dies. In other embodiments, however, any of the electrical connectors **328a-c** can be arranged differently (e.g., as previously discussed with respect to FIGS. 2A-2C), or can be omitted altogether. Additionally, the package **300** can include additional electrical connectors not shown in FIG. 3, such as electrical connectors between a die and the package substrate **104**.

Optionally, the package **300** can include one or more surface-mounted components **150**, such as capacitors, resistors, inductors, and/or other circuit elements. The surface-mounted components can be on the package substrate **104** (e.g., at peripheral portions away from the first and second die stacks **302a-b**), between the first and second die stacks **302a-b**, on the routing substrate **106**, or any other suitable location.

The package **300** can be manufactured using any suitable process known to those of skill in the art. In some embodiments, for example, a manufacturing process for the package **300** includes mounting the first and second die stacks **302a-b** on the package substrate **104**. The process further includes forming the redistribution structure **312** on the routing substrate **306** using wafer-level or chip-level processes. Subsequently, the routing substrate **306** is mounted on the first and second die stacks **302a-b** (e.g., via die attach film or other suitable techniques). The second die **310** can be mounted on the routing substrate **306** before, during, or after the routing substrate **306** is mounted on the first and second die stacks **302a-b**. The electrical connectors **328a-c** can then be formed and attached to the routing substrate **306**, the first and second die stacks **302a-b**, and the package substrate **104** to electrically couple these components to each other, as discussed above.

Although FIG. 3 illustrates a package **300** with a routing substrate **306** configured to transmit signals between two die stacks, in other embodiments, the package **300** can include a greater number of die stacks, such as three, four, five or more die stacks. In such embodiments, the routing substrate **306** can be mechanically and electrically coupled to each of the die stacks to route signals between the die stacks, a controller die (e.g., second die **310**), and/or the package substrate **104**.

Any one of the semiconductor devices and/or packages having the features described above with reference to FIGS. 1A-3 can be incorporated into any of a myriad of larger and/or more complex systems, a representative example of

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which is system **400** shown schematically in FIG. 4. The system **400** can include a processor **402**, a memory **404** (e.g., SRAM, DRAM, flash, and/or other memory devices), input/output devices **406**, and/or other subsystems or components **408**. The semiconductor dies and/or packages described above with reference to FIGS. 1A-3 can be included in any of the elements shown in FIG. 4. The resulting system **400** can be configured to perform any of a wide variety of suitable computing, processing, storage, sensing, imaging, and/or other functions. Accordingly, representative examples of the system **400** include, without limitation, computers and/or other data processors, such as desktop computers, laptop computers, Internet appliances, hand-held devices (e.g., palm-top computers, wearable computers, cellular or mobile phones, personal digital assistants, music players, etc.), tablets, multi-processor systems, processor-based or programmable consumer electronics, network computers, and minicomputers. Additional representative examples of the system **400** include lights, cameras, vehicles, etc. With regard to these and other example, the system **400** can be housed in a single unit or distributed over multiple interconnected units, e.g., through a communication network. The components of the system **400** can accordingly include local and/or remote memory storage devices and any of a wide variety of suitable computer-readable media.

From the foregoing, it will be appreciated that specific embodiments of the technology have been described herein for purposes of illustration, but that various modifications may be made without deviating from the disclosure. Accordingly, the invention is not limited except as by the appended claims. Furthermore, certain aspects of the new technology described in the context of particular embodiments may also be combined or eliminated in other embodiments. Moreover, although advantages associated with certain embodiments of the new technology have been described in the context of those embodiments, other embodiments may also exhibit such advantages and not all embodiments need necessarily exhibit such advantages to fall within the scope of the technology. Accordingly, the disclosure and associated technology can encompass other embodiments not expressly shown or described herein.

What is claimed:

1. A semiconductor assembly comprising:

a package substrate;

a die stack mounted on the package substrate, the die stack including a plurality of semiconductor dies;

a routing substrate mounted on the die stack, the routing substrate including an upper surface facing away from the die stack;

a redistribution structure formed above the upper surface of the routing substrate; and

an electrical connector coupling the redistribution structure to the die stack, wherein the die stack is electrically coupled to the package substrate via the redistribution structure and the electrical connector without a direct electrical connection between a lowermost die of the die stack and the package substrate.

2. The semiconductor assembly of claim 1, further comprising:

a controller die mounted on the routing substrate electrically coupled to the redistribution structure, wherein the plurality of semiconductor dies are electrically coupled to the controller die via the redistribution structure.

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3. The semiconductor assembly of claim 2, wherein an active surface of the controller die faces the redistribution structure.

4. The semiconductor assembly of claim 1, wherein the die stack is a first die stack and the plurality of semiconductor dies are first semiconductor dies, the semiconductor assembly further comprising:

a second die stack including a plurality of second semiconductor dies, wherein the routing substrate is mounted on both the first die stack and second die stack.

5. The semiconductor assembly of claim 4, wherein the first die stack and the second die stack are arranged in a shingled configuration, and wherein the first die stack and the second die stack are angled toward each other.

6. The semiconductor assembly of claim 1, wherein the redistribution structure includes a plurality of traces that respectively extend from a plurality of contacts at interior portion of the routing substrate to a plurality of bond pads at a peripheral portion of the routing substrate, wherein each of the plurality of contacts is coupled to a respective interconnect structure.

7. A semiconductor assembly, comprising:

a die stack including a plurality of semiconductor dies; a routing substrate mounted on the die stack, the routing substrate including an upper surface facing away from the die stack;

a redistribution structure formed above the upper surface of the routing substrate;

at least one electrical connector directly coupling the redistribution structure to at least some of the plurality of semiconductor dies of the die stack; and

a controller die mounted on the routing substrate and electrically coupled to the redistribution structure, wherein the plurality of semiconductor dies are electrically coupled to the controller die via the redistribution structure.

8. The semiconductor assembly of claim 7, wherein the routing substrate is a semiconductor die or an interposer.

9. The semiconductor assembly of claim 7, further comprising a plurality of interconnect structures coupling an active surface of the controller die to the redistribution structure.

10. The semiconductor assembly of claim 9, wherein the redistribution structure includes:

a plurality of contacts at an interior portion of the routing substrate, wherein each contact is coupled to a respective interconnect structure of the plurality of interconnect structures;

a plurality of bond pads at a peripheral portion of the routing substrate, wherein each bond pad is coupled to a respective electrical connector; and

a plurality of traces, wherein each trace connects a respective contact to a respective bond pad.

11. The semiconductor assembly of claim 9, wherein the active surface of the controller die is thermally bonded to the redistribution structure.

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12. The semiconductor assembly of claim 7, wherein the die stack is a first die stack and the plurality of semiconductor dies are first semiconductor dies, the semiconductor assembly further comprising:

a second die stack including a plurality of second semiconductor dies, wherein the routing substrate is mounted on the first and second die stacks such that the second semiconductor dies are electrically coupled to the controller die via the redistribution structure.

13. The semiconductor assembly of claim 12, wherein the first die stack and the second die stack are arranged in a shingled configuration, and wherein the first die stack and the second die stack are angled toward each other.

14. The semiconductor assembly of claim 7, further comprising a package substrate supporting the die stack, wherein the package substrate is coupled to the die stack and the controller die via the redistribution structure and the at least one electrical connector without a direct electrical connection between a lowermost die of the die stack and the package substrate.

15. The semiconductor assembly of claim 14, wherein the package substrate includes no more than two routing layers.

16. The semiconductor assembly of claim 7, wherein the at least one electrical connector includes (1) a first electrical connector directly coupling the redistribution structure and an uppermost die of the die stack and (2) a second electrical connector directly coupling the redistribution structure and a lower die of the die stack beneath the uppermost die.

17. The semiconductor assembly of claim 7, wherein the at least one electrical connector includes a first electrical connector directly coupling the redistribution structure and an uppermost die of the die stack, the semiconductor assembly further comprising: a second electrical connector directly coupling the uppermost die to a lower die of the die stack beneath the uppermost die.

18. A method of producing a semiconductor assembly, the method comprising:

mounting a die stack on a package substrate;

mounting a routing substrate on the die stack, the routing substrate including an upper surface facing away from the die stack;

forming a redistribution structure above the upper surface of the routing substrate;

attaching a first electrical connector from the redistribution structure to the package substrate; and

attaching a second electrical connector from the redistribution structure to the die stack, thereby electrically coupling the die stack to the package substrate via the redistribution structure without a direct electrical connection between a lowermost die of the die stack and the package substrate.

19. The method of claim 18, further comprising:

mounting a controller die above the upper surface of the routing substrate by coupling an active surface of the controller die to the redistribution structure using a thermocompression bonding process.

20. The method of claim 18, wherein the redistribution structure is formed using a wafer-level process.

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